Amendments to the Claims:

A listing of the entire set of pending claims (including amendments to the claims, if any) is submitted herewith per 37 CFR 1.121. This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended): A display device comprising:

a first substrate~~, said substrate is provided with~~ that includes groups of pixels ~~wherein each group of pixels is~~ within ~~a~~ separate defined areas on ~~said~~ the first substrate; and

a plurality of semiconductor integrated circuit (IC) devices that are fabricated on a second substrate,

wherein:

~~each semiconductor IC device is mainly associated with a different group of pixels, and wherein~~

each semiconductor IC device is positioned within the defined area of ~~the~~ an associated group of pixels ~~that it is mainly associated with~~, and

the semiconductor IC device ~~being provided with comprises drive means for driving~~ is configured to:

receive image data based on a first resolution that is substantially independent of the display device, and

drive pixels within the associate group based on a second resolution corresponding to the display device ~~pixels dependent on data to be displayed and with a picture scaling means~~.

2. (Currently amended): ~~A~~ The display device ~~as claimed in~~ of claim 1, wherein the ~~picture scaling means comprise means~~ semiconductor IC device is configured to determine ~~the kind of~~ a degree of scaling to be performed to effect an appropriate transformation from the first resolution to the second resolution.

3. (Currently Amended): ~~A~~ The display device ~~as claimed in~~ of claim 1, wherein the ~~picture scaling means~~ semiconductor IC device provides ~~several~~ two or more pixels within its associated group of pixels with ~~the same~~ a common data voltage[[~~s~~]].

4. (Currently amended): ~~A~~ The display device ~~as claimed in~~ of claim 3, wherein the ~~picture scaling means~~ semiconductor IC device determines intermediate voltages for neighboring pixels.

5. (Currently amended): ~~A~~ The display device ~~as claimed in~~ of claim 4, wherein the ~~picture scaling means~~ semiconductor IC device determines intermediate voltages for pixels in neighboring columns.

6. (Currently amended): ~~A~~ The display device ~~as claimed in~~ of claim 4, wherein the ~~picture scaling means~~ semiconductor IC device determines intermediate voltages for pixels in neighboring rows.

7. (Currently Amended): ~~A~~ The display device ~~as claimed in~~ of claim 4 ~~comprising a further~~, including connection between neighboring semiconductor IC devices on the first substrate.

8. (Currently amended): ~~A~~ The display device ~~as claimed in~~ of claim 4, wherein the ~~driving means comprise~~ semiconductor IC device includes a frame memory and ~~means~~ is configured to detect changes between the contents of subsequent frames.

9. (Currently amended): ~~A~~ The display device ~~as claimed in~~ of claim 1, wherein ~~the means for recognizing the~~ each semiconductor IC device is configured to recognize a location ~~comprise at least one of the~~ of its corresponding group ~~comprising~~ based on at least one of a read-only structure and a programmable memory.

10. (Currently amended): ~~A~~ The display device ~~as claimed in~~ of claim 1, ~~wherein the drive means have~~ including a bus structure for communicating with the plurality of semiconductor IC devices.

11. (New) A method of fabricating a display device, comprising:

fabricating a plurality of groups of pixel electrodes on a first substrate,

fabricating a plurality of IC (Integrated Circuit) circuits on a second substrate, and

attaching an IC circuit of the plurality of IC circuits to a corresponding group of pixel electrodes on the second substrate,

wherein

the fabrication of each IC circuit includes configuring each IC circuit to scale image data based on a resolution of the display device, and drive each electrode of the corresponding group of pixel electrodes accordingly.

12. (New) The method of claim 11, including

detaching the IC circuit from the second substrate.

13. (New) The method of claim 12, including

attaching a third substrate and a liquid crystal material that is disposed between the first substrate and the third substrate.

14. (New) The method of claim 11, wherein

the fabrication of each IC circuit includes configuring each IC circuit to receive information to facilitate determining the resolution of the display device.

15. (New) The method of claim 11, wherein

the fabrication of each IC circuit includes configuring each IC circuit to receive information to facilitate determining a location of the corresponding group of pixel electrodes.

16. (New) The method of claim 11, wherein

the fabrication of each IC circuit includes configuring each IC circuit to determine and provide a common voltage to two or more pixel electrodes of the corresponding group of pixel electrodes.

17. (New) The method of claim 11, wherein

the fabrication of each IC circuit includes configuring each IC circuit to determine and provide an intermediate voltage to neighboring pixel electrodes of the corresponding group of pixel electrodes.

18. (New) The method of claim 11, wherein

the fabrication of the groups of pixels on the first substrate includes fabricating a bus structure on the first substrate for communications among the plurality of IC circuits.